

ESD Protection Diodes Silicon Epitaxial Planar

# DF2S6P2CTC

#### General

The DF2S6P2CTC is a TVS diode (ESD protection diode) protects semiconductor devices used in mobile device interfaces and other applications to protect against static electricity and noise.

The DF2S6P2CTC has realized high  $I_{PP}$ , in order to protect a semiconductor devices from the indirect lightning stroke and the transition voltage (at the time of power activation).

Furthermore, the DF2S6P2CTC is housed in an ultra-compact package (1.6 mm  $\times$  0.8 mm) to meet applications that require a small footprint.

#### 2. Applications

Mobile Equipment

- · Smartphones
- · Tablets
- · Notebook PCs

Desktop PCs

Note: This product is designed for protection against electrostatic discharge (ESD) and is not intended for any other purpose, including, but not limited to, voltage regulation.

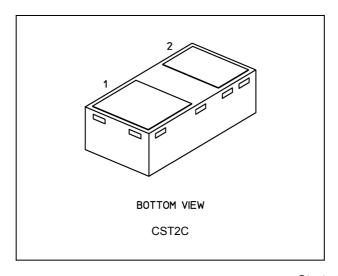
#### 3. Features

- (1) Suitable for use with a 5.0 V signal line.  $(V_{RWM} \le 5.5 \text{ V})$
- (2) Protects devices with its high ESD performance.

 $(\ensuremath{\mathrm{V_{ESD}}} = \pm 30~\ensuremath{\mathrm{kV}}$  (Contact / Air) @IEC61000-4-2)

- (3) Low dynamic resistance protects semiconductor devices from static electricity and noise.  $(R_{DYN} = 0.08 \Omega \text{ (typ.)})$
- (4) Snapback characteristics realizing low clamping voltage protects semiconductor devices.  $(V_C = 18 \text{ V@I}_{PP} = 80 \text{ A (typ.)})$
- (5) Compact package is suitable for use in high density board layouts such as in mobile devices.  $(1.6 \text{ mm} \times 0.8 \text{ mm} \text{ size} \text{ (Nickname: CST2C))}$

#### 4. Packaging

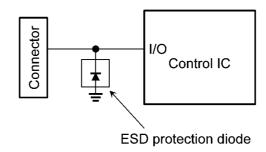


Start of commercial production

2018-04



#### 5. Example of Circuit Diagram

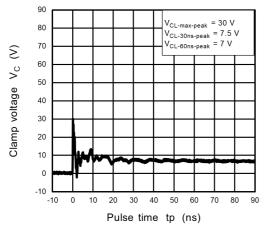


#### 6. Quick Reference Data

Characteristics	Symbol	Note	Test Condition	Min	Тур.	Max	Unit
Working peak reverse voltage	$V_{RWM}$	(Note 1)	_	_	_	5.5	V
Dynamic resistance	$R_{DYN}$	(Note 2)	_	_	0.08	_	Ω
Electrostatic discharge voltage (IEC61000-4-2) (Contact)	V <sub>ESD</sub>	(Note 3)	_		-	30	kV

- Note 1: Recommended operating condition.
- Note 2: TLP parameters:  $Z0 = 50 \Omega$ , tp = 100 ns, tr = 300 ps, averaging window: t1 = 30 ns to t2 = 60 ns, extraction of dynamic resistance using least squares fit of TLP characteristics between  $I_{PP1} = 16$  A and  $I_{PP2} = 30$  A.
- Note 3: Criterion: No damage to devices.

#### 6.1. ESD Clamp Waveform (Note)





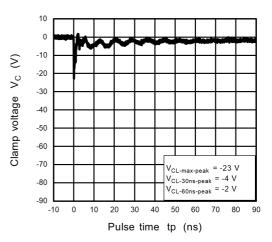


Fig. 6.1.2 -8 kV

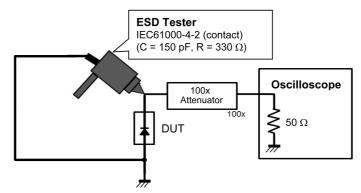


Fig. 6.1.3 IEC61000-4-2 (Contact)

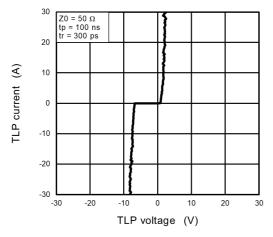
Note: The above characteristics curves are presented for reference only and not guaranteed by production test, unless otherwise noted.

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Rev.3.0



### 6.2. TLP Characteristics (Note)



Note: The above characteristics curves are presented for reference only and not guaranteed by production test, unless otherwise noted.

### 6.3. Clamp Voltage - Peak Pulse Current (V<sub>C</sub> - I<sub>PP</sub>) (Note)

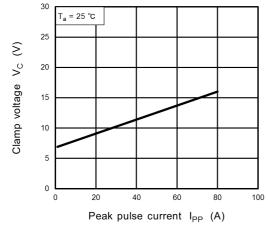


Fig. 6.3.1 V<sub>C</sub> - I<sub>PP</sub>

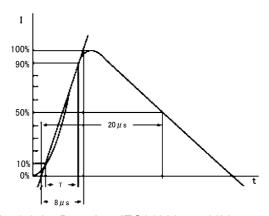


Fig. 6.3.2 Based on IEC61000-4-5 8/20  $\mu$ s pulse.

Note: The above characteristics curves are presented for reference only and not guaranteed by production test, unless otherwise noted.

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### 7. Absolute Maximum Ratings (Note) (Unless otherwise specified, Ta = 25 °C)

Characteristics	Symbol	Note	Rating	Unit
Electrostatic discharge voltage (IEC61000-4-2) (Contact)	V <sub>ESD</sub>	(Note 1)	±30	kV
Electrostatic discharge voltage (IEC61000-4-2) (Air)			±30	
Peak pulse power (tp = 8/20 μs)	P <sub>PK</sub>		1900	W
Peak pulse current (tp = 8/20 μs)	I <sub>PP</sub>	(Note 2)	80	Α
Junction temperature	Tj		150	°C
Storage temperature	T <sub>stg</sub>		-55 to 150	°C

Note: Using continuously under heavy loads (e.g. the application of high temperature/current/voltage and the significant change in temperature, etc.) may cause this product to decrease in the reliability significantly even if the operating conditions (i.e. operating temperature/current/voltage, etc.) are within the absolute maximum ratings.

Please design the appropriate reliability upon reviewing the Toshiba Semiconductor Reliability Handbook ("Handling Precautions"/"Derating Concept and Methods") and individual reliability data (i.e. reliability test report and estimated failure rate, etc).

Note 1: According to IEC61000-4-2.

Note 2: According to IEC61000-4-5.

### 8. Electrical Characteristics (Unless otherwise specified, T<sub>a</sub> = 25 °C)

V<sub>RWM</sub>: Working peak reverse voltage V<sub>BR</sub>: Reverse breakdown voltage I<sub>BR</sub>: Reverse breakdown current

I<sub>R</sub>: Reverse current V<sub>C</sub>: Clamp voltage I<sub>PP</sub>: Peak pulse current R<sub>DYN</sub>: Dynamic resistance

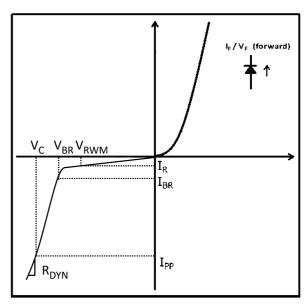


Fig. 8.1 Definitions of Electrical Characteristics

Characteristics	Symbol	Note	Test Condition	Min	Тур.	Max	Unit
Working peak reverse voltage	$V_{RWM}$	(Note 1)	_	_	_	5.5	V
Total capacitance	Ct		V <sub>R</sub> = 0 V, f = 1 MHz	_	600	_	pF
Dynamic resistance	$R_{DYN}$	(Note 2)	_	_	0.08	_	Ω
Reverse breakdown voltage	$V_{BR}$		I <sub>BR</sub> = 1 mA	5.6	6.7	8.0	V
Reverse current	I <sub>R</sub>		V <sub>RWM</sub> = 5.5 V	_	_	0.1	μА
Clamp voltage	V <sub>C</sub>	(Note 3)	I <sub>PP</sub> = 1 A	_	7	_	V
			I <sub>PP</sub> = 80 A	_	18	23.7	
		(Note 2)	I <sub>TLP</sub> = 16 A	_	7.8	_	V
			I <sub>TLP</sub> = 30 A	_	8.8	_	

Note 1: Recommended operating condition.

Note 2: TLP parameters:  $Z0 = 50 \Omega$ , tp = 100 ns, tr = 300 ps, averaging window: t1 = 30 ns to t2 = 60 ns, extraction of dynamic resistance using least squares fit of TLP characteristics between  $I_{PP1} = 16$  A and  $I_{PP2} = 30$  A.

Note 3: Based on IEC61000-4-5 8/20  $\mu$ s pulse.

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### 9. Characteristics Curves (Note)

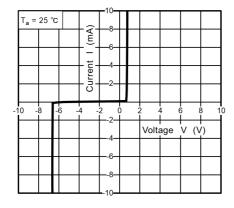


Fig. 9.1 I-V

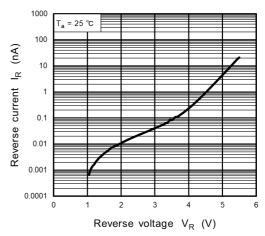


Fig. 9.2 I<sub>R</sub> - V<sub>R</sub>

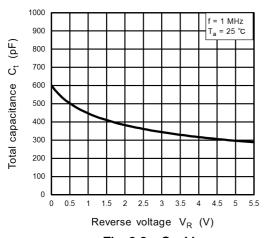
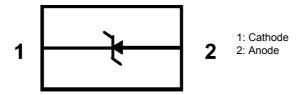


Fig. 9.3 Ct - VR

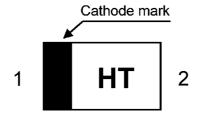
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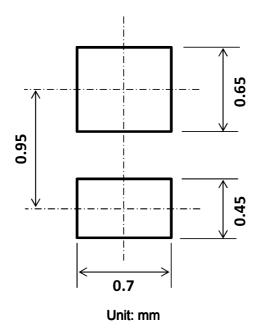
#### 10. Internal Circuit



### 11. Marking (Top view)



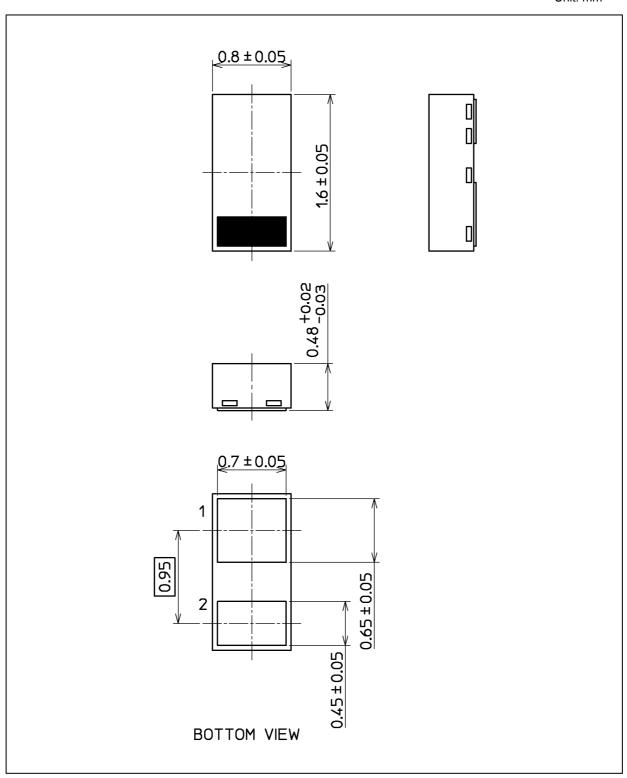
### 12. Land Pattern Dimensions (for reference only)





### **Package Dimensions**

Unit: mm



Weight: 1.5 mg (typ.)

	Package Name(s)
Nickname: CST2C	



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